



Part Number: XZM2ACR55W-3

3.2x1.6mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Features

•3.2mmx1.6mm SMT LED,1.8mm thickness.

•Low power consumption.

•Ideal for backlight and indicator.

•Various colors and lens types available.

•Package : 2000pcs / reel.

•Moisture sensitivity level : level 3.

 \bullet RoHS compliant.

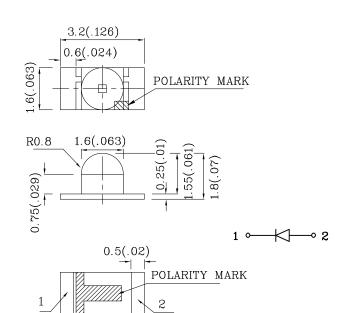




Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.2(0.008") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Rating (TA=25°C)	M2ACR (AlInGaP)	Unit			
Reverse Voltage	VR	5	V		
Forward Current	IF	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA		
Power Dissipation	Рт	84	mW		
Operating Temperature	TA	-40 ~ +85	°C		
Storage Temperature	Tstg	-40 ~ +85			



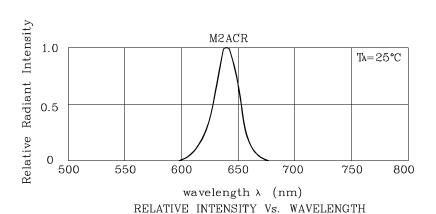
Operating Characteristic (TA=25°C)	M2ACR (AlInGaP)	Unit	
Forward Voltage (Typ.) (IF=20mA)	VF	2.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.8	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	640	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	630	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	25	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	27	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Lumi Inter (IF=2 me	nsity 0mA)	Wavelength nm λ P	Viewing Angle 2 0 1/2
				min.	typ.		
XZM2ACR55W-3	Red	AlInGaP	Water Clear	3800	6490	640	50°
Published Date : I	DEC 15, 2008	Drawin	g No : XDSB2648	V1	Check	ed : B.L.LIU	P.1/4

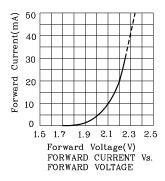


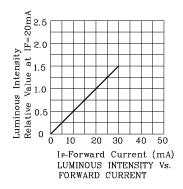
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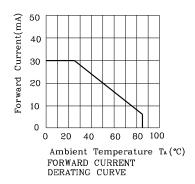


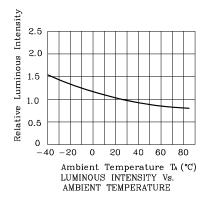


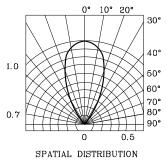
❖ M2ACR











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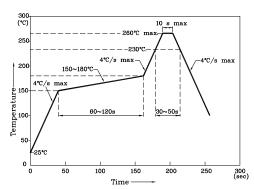


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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

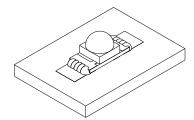
Reflow Soldering Profile For Lead-free SMT Process.



NOTES

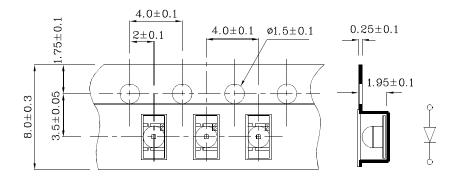
- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- 3. Do not put stress to the epoxy resin during high temperatures conditions.
- ❖ Recommended Soldering Pattern (Units: mm; Tolerance: ±0.1)
- **❖** The device has a single mounting surface. The device must be mounted according to the specifications.





* Tape Specification (Units:mm)

TAPE



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

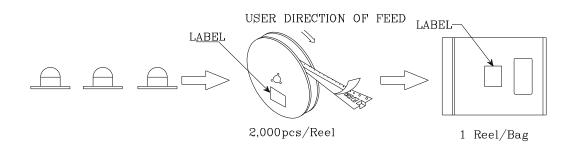


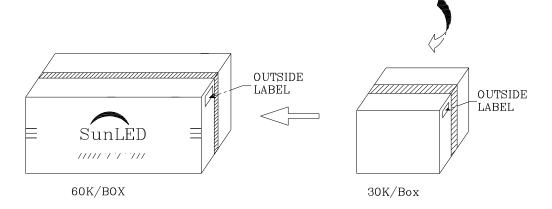
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PACKING & LABEL SPECIFICATIONS

XZM2ACR55W-3







QTY: 2,000 pcs CODE: XXX

S/N : XX

LOT NO:



RoHS Compliant

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